

customer	
pcb name	
WE article number	
engineer	
date	



Multilayer 8 Layers

PCB Thickness : 1,60 mm +/- 10%

Rigid area Structure	Rigid area Thickness	Material description	Via types	Layer usage	Impedance	
					Er	Z[Ohm] Line / Space
Soldermask	15					
L1	45	* Incl. Plating	Top-Layer		3,5	
	230	FR4 TG 135			3,9	
L2	18					
	150	FR4 TG 135			3,9	
L3	18					
	230	FR4 TG 135			3,9	
L4	18					
	150	FR4 TG 135			3,9	
L5	18					
	230	FR4 TG 135			3,9	
L6	18					
	150	FR4 TG 135			3,9	
L7	18					
	230	FR4 TG 135			3,9	
L8	45	* Incl. Plating	Bottom-Layer			
Soldermask	15				3,5	

Notes:  
 50 % copper occupancy IL  
 final copper thickness according to IPC 6012  
 Dielectric material according IPC-4101 E / 24  
 For Microvia technology please use our HDI stackups

Revision: Created: W. Brylka / Scrutinised: A. Schilpp / Approved: A.Schilpp  
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Via types - Standard and options

